

POWERED BY Dialog



Resin seal-type semiconductor device with improved reliability - has metallic foil wiring lead with lead terminal, semiconductor chip electrically connected to lead terminal and two packages arranged on surface

Patent Assignee: TOSHIBA KK

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 6318609	A	19941115	JP 93106865	A	19930507	199505	B

Priority Applications (Number Kind Date): JP 93106865 A (19930507)

Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
JP 6318609	A		6	H01L-021/56	

Abstract:

JP 6318609 A

The device comprises a metallic foil wiring lead (6) having a lead terminal (7), a semiconductor chip (3) electrically connected to the lead terminal (7) of the metallic foil wiring lead (6), a first package (21) arranged on the surface of the side where the metallic foil wiring lead (6) is connected to the lead terminal (7) which is connected to the semiconductor chip (3) and formed by pressure-moulding uncured resin to give a seal having an area lower than that of the connection surface side of the semiconductor tip (3), and a second package (22) arranged on the surface of the side where the semiconductor chip (3) is not connected to the lead terminal (7) and formed by pressure-moulding uncured resin to give a seal having an area larger than that of the non-connection surface side of the semiconductor chip (3).

ADVANTAGE - Edge touch between a metallic foil wiring lead and a semiconductor chip does not occur and reliability is improved.

Dwg. 1/3

Derwent World Patents Index

© 2002 Derwent Information Ltd. All rights reserved.

Dialog® File Number 351 Accession Number 10132231

RECEIVED
JAN 23 2002
TECHNOLOGY CENTER 2800